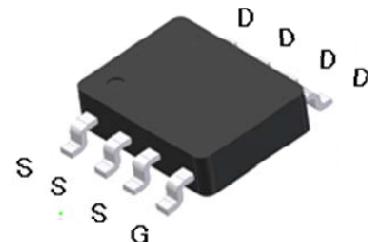
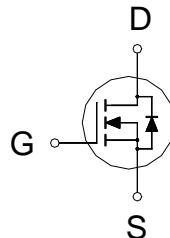


**N-Channel Logic Level Enhancement Mode Field Effect Transistor**
**Product Summary:**

$BV_{DSS}$	60V
$R_{DS(on)}$ (MAX.)	55m $\Omega$
$I_D$	6A

UIS,  $R_g$  100% Tested

Pb-Free Lead Plating &amp; Halogen Free


**ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	$I_D$	6	A
	$T_A = 100^\circ\text{C}$		4.5	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	24	
Avalanche Current		$I_{AS}$	6	
Avalanche Energy	$L = 0.1\text{mH}, I_D=6\text{A}, R_G=25\Omega$	$E_{AS}$	1.8	mJ
Repetitive Avalanche Energy <sup>2</sup>	$L = 0.05\text{mH}$	$E_{AR}$	0.9	
Power Dissipation	$T_A = 25^\circ\text{C}$	$P_D$	2.5	W
	$T_A = 100^\circ\text{C}$		1	
Operating Junction & Storage Temperature Range		$T_j, T_{stg}$	-55 to 150	°C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$	25	50	°C / W
Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$			

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle  $\leq 1\%$ 
<sup>3</sup>50°C / W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.

**ELECTRICAL CHARACTERISTICS ( $T_c = 25^\circ\text{C}$ , Unless Otherwise Noted)**

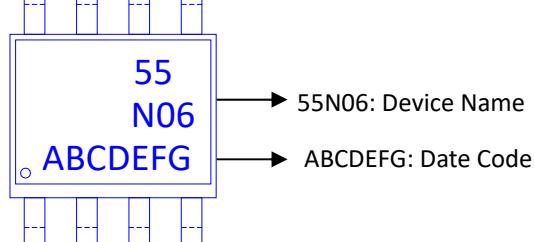
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	2.0	3.2	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 48V, V_{GS} = 0V$			1	$\mu\text{A}$
		$V_{DS} = 40V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			25	
On-State Drain Current <sup>1</sup>	$I_{D(\text{ON})}$	$V_{DS} = 5V, V_{GS} = 10V$	6			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(\text{ON})}$	$V_{GS} = 10V, I_D = 6A$		45	55	$\text{m}\Omega$
		$V_{GS} = 5V, I_D = 5A$		52	70	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 6A$		12		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 30V, f = 1\text{MHz}$		633		$\text{pF}$
Output Capacitance	$C_{oss}$			67		
Reverse Transfer Capacitance	$C_{rss}$			44		
Total Gate Charge <sup>1,2</sup>	$Q_g$	$V_{DS} = 30V, V_{GS} = 10V, I_D = 6A$		13.8		$\text{nC}$
Gate-Source Charge <sup>1,2</sup>	$Q_{gs}$			2.8		
Gate-Drain Charge <sup>1,2</sup>	$Q_{gd}$			4.0		
Turn-On Delay Time <sup>1,2</sup>	$t_{d(\text{on})}$	$V_{DS} = 30V, I_D = 1A, V_{GS} = 10V, R_{GS} = 6\Omega$		10		$\text{nS}$
Rise Time <sup>1,2</sup>	$t_r$			7.5		
Turn-Off Delay Time <sup>1,2</sup>	$t_{d(\text{off})}$			15		
Fall Time <sup>1,2</sup>	$t_f$			10		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_c = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_S$				2.3	$\text{A}$
Pulsed Current <sup>3</sup>	$I_{SM}$				9.2	
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = I_S, V_{GS} = 0V$			1.2	V

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .<sup>2</sup>Independent of operating temperature.<sup>3</sup>Pulse width limited by maximum junction temperature.

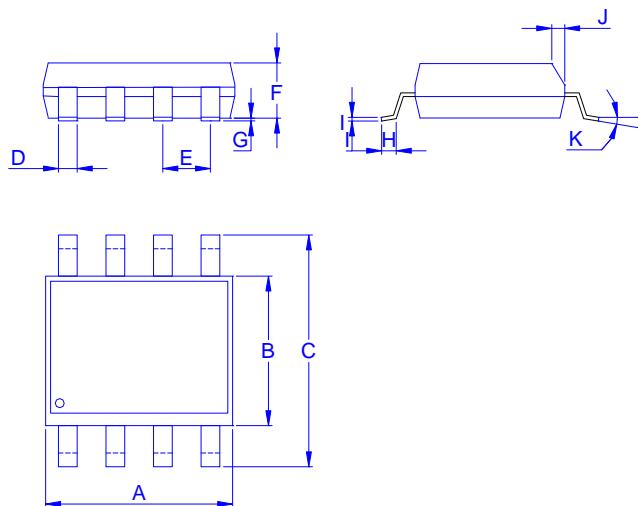
## Ordering & Marking

### Information:

Device Name: LB55N06H for SOP-8



### Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
Min.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°

